

In the Claims

Applicant has submitted a new complete claim set.

Please cancel claims 1-15 without prejudice or disclaimer.

1-15 (canceled)

16. (original) A method comprising:

deforming a flexible metal structure from a first configuration to a second configuration;
and

depositing auxiliary metal on the metal structure to the extent that the structure is self-supporting in the second configuration.

17. (original) The method of claim 16 wherein the flexible metal structure is disposed on photographic film.

18. (original) The method of claim 17 further comprising freeing the structure from the photographic film.

19. (original) A method comprising:

exposing photoresist to electromagnetic radiation through a metal mask;
developing the photoresist thereby forming a photoresist pattern;
directing a metal deposition composition to the metal mask via the photoresist pattern;
and
depositing auxiliary metal on the metal mask from the deposition composition.

20. (original) The method of claim 19 wherein the metal mask is produced by selectively exposing portions of the mask to electromagnetic radiation and adding metal to the same or to alternate portions of the mask using electroless deposition.

21. (original) The method of claim 19 wherein the auxiliary metal is deposited via electroplating.
22. (original) The method of claim 19 wherein the metal is in the form of a pattern and at least a portion of the pattern has an aspect ratio of greater than or equal to about 5.
23. (original) A method of forming a conductive pattern, comprising:
 illuminating a photographic film with a desired illumination configuration;
 developing the photographic film so that illuminated or non-illuminated portions of the film are adjusted to be in an altered state; and
 selectively depositing additional conductive material onto portions of the film in an altered state in amounts greater than amounts of conductive material deposited on portions of the film not in the altered state.
24. (original) The method of claim 23 wherein the additional conductive material is deposited via electroless deposition.
25. (original) The method of claim 24 further comprising electroplating additional metal on the metal deposited via the electroless deposition.
26. (original) The method of claim 23 wherein the conductive pattern is a circuit.
27. (original) A method of forming a discontinuous metallic structure comprising:
 illuminating a photographic film with a desired structure configuration;
 developing the photographic film so that illuminated or non-illuminated portions of the film are adjusted to be in an altered state; and
 selectively depositing additional conductive material onto portions of the film in an altered state in amounts greater than amounts of conductive material deposited on portions of the film not in the altered state.

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28. (original) The method of claim 27 wherein the additional conductive material is deposited via electroless deposition.

29. (original) The method of claim 28 wherein the additional conductive material is nickel.